# PR26MF21NSZ Series **PR36MF2xNSZ** Series

\*Non-zero cross type is also available. (PR26MF1xNSZ Series/ PR36MF1xNSZ Series)

# I<sub>T</sub>(rms)≤0.6A, Zero Cross type **DIP 8pin Triac output SSR**



#### Description

PR26MF21NSZ Series and PR36MF2xNSZ Series Solid State Relays (SSR) are an integration of an infrared emitting diode (IRED), a Phototriac Detector and a main output Triac. These devices are ideally suited for controlling high voltage AC loads with solid state reliability while providing 4.0kV isolation (V<sub>iso</sub>(rms)) from input to output.

#### Features

- 1. Output current, I<sub>T</sub>(rms)≤0.6A
- 2. Zero crossing functionary (Vox : MAX. 35V)
- 3. 8 pin DIP package (SMT gullwing also available)
- 4. High repetitive peak off-state voltage (V<sub>DRM</sub>: 600V, PR36MF2xNSZ Series) (V<sub>DBM</sub>: 400V, PR26MF21NSZ Series)
- 5. IFT ranks available (see Model Line-up in this datasheet)
- 6. Superior noise immunity (dV/dt : MIN. 100V/µs)
- 7. Response time, ton : MAX. 50µs
- 8. Lead-free terminal components are also available (see Model Line-up section in this datasheet)
- 9. High isolation voltage between input and output  $(V_{iso}(rms) : 4.0kV)$

#### Agency approvals/Compliance

- 1. Recognized by UL508, file No. E94758 (as model No. R26MF2/R36MF2)
- 2. Approved by CSA 22.2 No.14, file No. LR63705 (as model No. R26MF2/R36MF2)
- 3. Optionary available VDE approved (\*)(DIN EN 60747-5-2), file No. 40008898 (only for PR36MF2xNSZ Series as model No. R36MF2)
- 4. Package resin : UL flammability grade (94V-0)
  - (\*) DIN EN60747-5-2 : successor standard of DIN VDE0884. Up to Date code "RD" (December 2003), approval of DIN VDE0884. From Date code "S1" (January 2004), approval of DIN EN60747-5-2.

### Applications

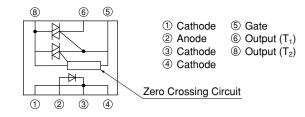
- 1. Isolated interface between high voltage AC devices and lower voltage DC control circuitry.
- 2. Switching motors, fans, heaters, solenoids, and valves.
- 3. Power control in applications such as lighting and temperature control equipment.

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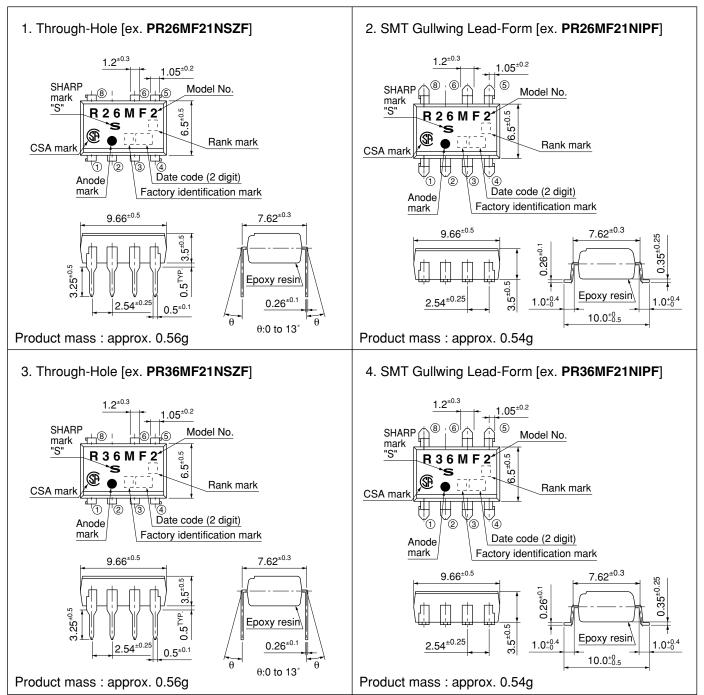


#### Internal Connection Diagram



#### Outline Dimensions

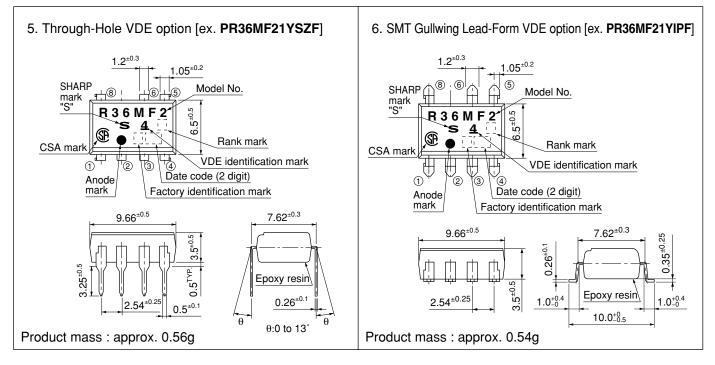
(Unit : mm)





# Outline Dimensions

(Unit : mm)





#### Date code (2 digit)

1st o	digit		2nd digit						
Year of p	roduction		Month of production						
Mark	A.D	Mark	Month	Mark					
А	2002	Р	January	1					
В	2003	R	February	2					
С	2004	S	March	3					
D	2005	Т	April	4					
Е	2006	U	May	5					
F	2007	V	June	6					
Н	2008	W	July	7					
J	2009	Х	August	8					
K	2010	А	September	9					
L	2011	В	October	0					
М	2012	С	November	N					
N	:	:	December	D					
	Year of p Mark A B C D E F H J K J K L M	A     2002       B     2003       C     2004       D     2005       E     2006       F     2007       H     2008       J     2009       K     2010       L     2011       M     2012	Year of production       Mark     A.D     Mark       A     2002     P       B     2003     R       C     2004     S       D     2005     T       E     2006     U       F     2007     V       H     2008     W       J     2009     X       K     2010     A       L     2011     B       M     2012     C	Year of productionMonth of productionMarkA.DMarkMonthA2002PJanuaryB2003RFebruaryC2004SMarchD2005TAprilE2006UMayF2007VJuneH2008WJulyJ2009XAugustK2010ASeptemberL2012CNovember					

repeats in a 20 year cycle

#### Factory identification mark

Factory identification Mark	Country of origin
no mark	Ionon
	Japan

\* This factory marking is for identification purpose only.

Please contact the local SHARP sales representative to see the actural status of the production.

#### Rank mark

Please refer to the Model Line-up table.

# PR26MF21NSZ Series PR36MF2xNSZ Series

#### Absolute Maximum Ratings

Abs	olute Maximu	m Ratings		(	$\Gamma_a=25^{\circ}C)$
	Parameter		Symbol	Rating	Unit
Innut	Forward current	I <sub>F</sub>	50 <sup>*3</sup>	mA	
Input	Reverse voltage		VR	6	V
	RMS ON-state cu	I <sub>T</sub> (rms)	0.6 *3	А	
Outrout	Peak one cycle su	I <sub>surge</sub>	6 *4	А	
Output	Repetitive	petitive PR26MF21NSZ		400	N7
	peak OFF-state voltage	PR36MF2xNSZ	Vdrm	600	V
*1Isolatio	on voltage		V <sub>iso</sub> (rms)	4.0	kV
Operati	ng temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage	temperature	T <sub>stg</sub>	-40 to +125	°C	
*2Solderi	ng temperature	T <sub>sol</sub>	270 *5	°C	

1 mm Soldering area

\*1 40 to 60%RH, AC for 1minute, f=60Hz

\*2 For 10s

\*3 Refer to Fig.1, Fig.2 \*4 f=50Hz sine wave \*5 Lead solder plating models: 260°C

# Electro-optical Characteristics

 $(T_a=25^{\circ}C)$ 

	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
т.,	Forward voltage		V <sub>F</sub>	I <sub>F</sub> =20mA		1.2	1.4	V
Input	Reverse current		I <sub>R</sub>	V <sub>R</sub> =3V	_	-	10	μΑ
	Repetitive peak OFF-state c	urrent	I <sub>DRM</sub>	$V_D = V_{DRM}$	-	-	100	μΑ
	ON-state voltage		VT	I <sub>T</sub> =0.6A	-	-	3.0	V
Output	Holding current		I <sub>H</sub>	V <sub>D</sub> =6V	-	-	25	mA
Output	Critical rate of rise of OFF-state voltage		dV/dt	$V_D=1/\sqrt{2} \cdot V_{DRM}$	100	-	-	V/µs
	Zero cross voltage	Rank 1	- V <sub>ox</sub>	I <sub>F</sub> =15mA, Resistance load		-	35	v
		Rank 2		I <sub>F</sub> =10mA, Resistance load				
	Minimum triagan aumont	Rank 1	IFT	$V_D=6V, R_L=100\Omega$	_	_	10	
Transfer	Minimum trigger current	Rank 2	161	VD=0V, KL=10052	_	_	5	mA
charac-	Isolation resistance		R <sub>ISO</sub>	DC500V,40 to 60%RH	$5 \times 10^{10}$	1011	-	Ω
teristics	Turn-on time	Rank 1	t	$I_F=20mA, V_D=6V, R_L=100\Omega$			50	
		Rank 2	t <sub>on</sub>	$I_{F}=10mA, V_{D}=6V, R_{L}=100\Omega$	-	_	50	μs



#### ■ Model Line-up (1) (Lead-free terminal components)

Lead Form	Throug	gh-Hole SM		SMT Gullwing			
China in a Daalaaa	Sleeve		Taping				I <sub>FT</sub> [mA]
Shipping Package	50pcs/sleeve 1 000pcs/reel		V <sub>DRM</sub>	Rank mark	$(V_D=6V,$		
DIN					[V]		$R_L=100\Omega)$
EN60747-5-2		Approved		Approved			
	PR36MF21NSZF	PR36MF21YSZF	PR36MF21NIPF	PR36MF21YIPF	(00	1	MAX.10
	PR36MF22NSZF	PR36MF22YSZF	PR36MF22NIPF	PR36MF22YIPF	600	2	MAX.5
	PR26MF21NSZF		PR26MF21NIPF		400	1	MAX.10

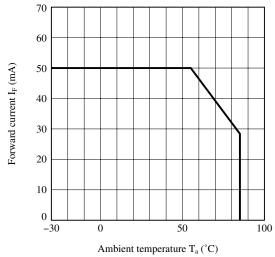
# ■ Model Line-up (2) (Lead solder plating components)

Lead Form	Throug	h-Hole	SMT G	ullwing			
	Sleeve		Taping				I <sub>FT</sub> [mA]
Shipping Package	hipping Package 50pcs/sleeve 1 000pcs/reel		V <sub>DRM</sub>	Rank mark	$(V_D=6V,$		
DIN	DIN				[V]		$R_L=100\Omega)$
EN60747-5-2		Approved		Approved			
	PR36MF21NSZ	PR36MF21YSZ			(00	1	MAX.10
Model No.	PR36MF22NSZ	PR36MF22YSZ			600	2	MAX.5
	PR26MF21NSZ				400	1	MAX.10

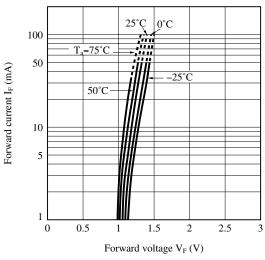
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Fig.1 Forward Current vs. Ambient Temperature









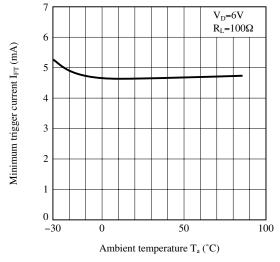


Fig.2 RMS ON-state Current vs. Ambient Temperature

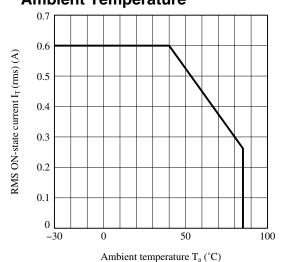


Fig.3-b Forward Current vs. Forward Voltage (Rank 2)

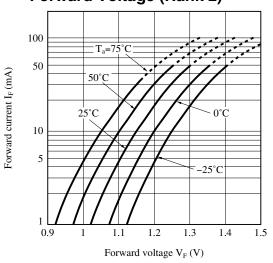
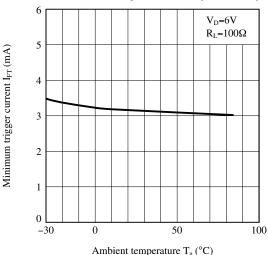
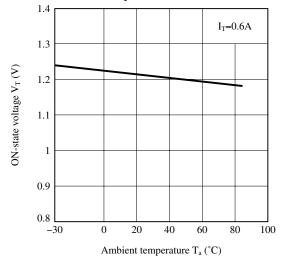


Fig.4-b Minimum Trigger Current vs. Ambient Temperature (Rank 2)

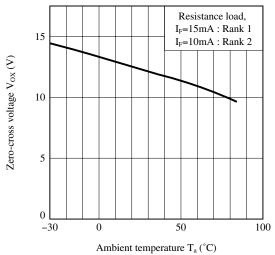


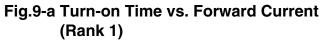


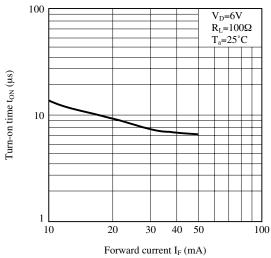
#### Fig.5 ON-state Voltage vs. Ambient Temperature



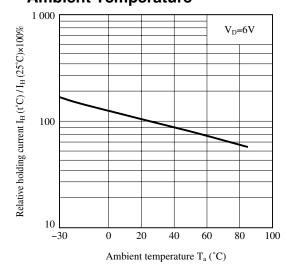








#### Fig.6 Relative Holding Current vs. Ambient Temperature



#### Fig.8 ON-state Current vs. ON-state Voltage

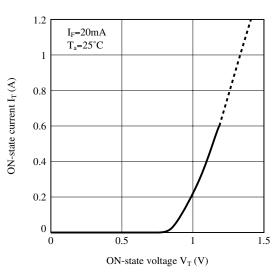
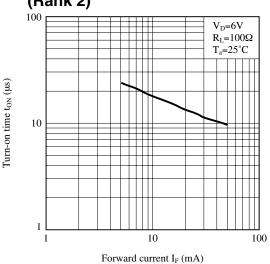
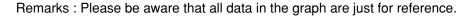


Fig.9-b Turn-on Time vs. Forward Current (Rank 2)







# Design Considerations Recommended Operating Conditions

	Parameter		Symbol	Conditions	MIN.	MAX.	Unit
Input	Input signal current Ran				20	25	
	at ON state Rank 2		$I_{\rm F}({\rm ON})$	_	10	15	mA
	Input signal current at OFF state		I <sub>F</sub> (OFF)	_	0	0.1	mA
	I and supply voltage	PR26MF21NSZ	V (mag)		_	120	V
	Load supply voltage	PR36MF2xNSZ	V <sub>OUT</sub> (rms)	_		240	
Output	Load supply current		I <sub>OUT</sub> (rms)	Locate snubber circuit between output terminals (Cs= $0.022\mu$ F, Rs= $47\Omega$ )	_	I <sub>T</sub> (rms)×80%(*)	mA
	Frequency		f	_	50	60	Hz
Operati	ng temperature		T <sub>opr</sub>	_	-20	80	°C

(\*) See Fig.2 about derating curve ( $I_T$ (rms) vs. ambient temperature).

#### • Design guide

In order for the SSR to turn off, the triggering current  $(I_F)$  must be 0.1mA or less.

Particular attention needs to be paid when utilizing SSRs that incorporate zero crossing circuitry.

If the phase difference between the voltage and the current at the output pins is large enough, zero crossing type SSRs cannot be used. The result, if zero crossing SSRs are used under this condition, is that the SSR may not turn on and off irregardless of the input current. In this case, only a non zero cross type SSR should be used in combination with the above mentioned snubber circuit selection process.

When the input current (I<sub>F</sub>) is below 0.1mA, the output Triac will be in the open circuit mode. However, if the voltage across the Triac, V<sub>D</sub>, increases faster than rated dV/dt, the Triac may turn on. To avoid this situation, please incorporate a snubber circuit. Due to the many different types of load that can be driven, we can merely recommend some circuit values to start with : Cs=0.022 $\mu$ F and Rs=47 $\Omega$ . The operation of the SSR and snubber circuit should be tested and if unintentional switching occurs, please adjust the snubber circuit component values accordingly.

When making the transition from On to Off state, a snubber circuit should be used ensure that sudden drops in current are not accompanied by large instantaneous changes in voltage across the Triac. This fast change in voltage is brought about by the phase difference between current and voltage. Primarily, this is experienced in driving loads which are inductive such as motors and solenods. Following the procedure outlined above should provide sufficient results.

For over voltage protection, a Varistor may be used.

Any snubber or Varistor used for the above mentioned scenarios should be located as close to the main output triac as possible.

All pins shall be used by soldering on the board. (Socket and others shall not be used.)

#### Degradation

In general, the emission of the IRED used in SSR will degrade over time.

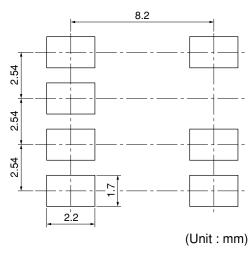
In the case where long term operation and / or constant extreme temperature fluctuations will be applied to the devices, please allow for a worst case scenario of 50% degradation over 5years.

Therefore in order to maintain proper operation, a design implementing these SSRs should provide at least twice the minimum required triggering current from initial operation.

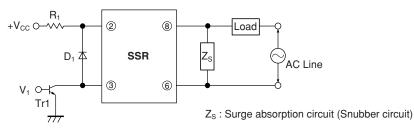


# • Recommended Foot Print (reference)

### SMT Gullwing Lead-form



#### Standard Circuit



☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

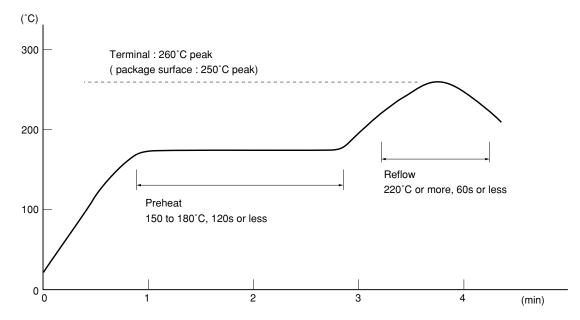


#### Manufacturing Guidelines

#### Soldering Method

**Reflow Soldering:** 

Reflow soldering should follow the temperature profile shown below. Soldering should not exceed the curve of temperature profile and time. Please don't solder more than twice.



#### Flow Soldering :

Flow soldering should be completed below 270°C and within 10s. Preheating is within the bounds of 100 to 150°C and 30 to 80s. Please don't solder more than twice.

#### Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C. Please don't solder more than twice.

#### Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



#### • Cleaning instructions

Solvent cleaning :

Solvent temperature should be 45°C or below. Immersion time should be 3minutes or less.

#### Ultrasonic cleaning :

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

#### Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

#### • Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform) Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.



# Package specification

# Sleeve package

# Through-Hole

Package materials Sleeve : HIPS (with anti-static material) Stopper : Styrene-Elastomer

## Package method

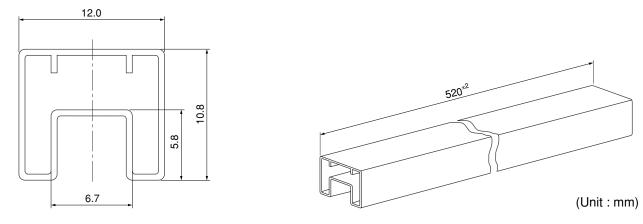
MAX. 50pcs of products shall be packaged in a sleeve.

Both ends shall be closed by tabbed and tabless stoppers.

The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.

MAX. 20 sleeves in one case.

# Sleeve outline dimensions





#### • Tape and Reel package

#### SMT Gullwing

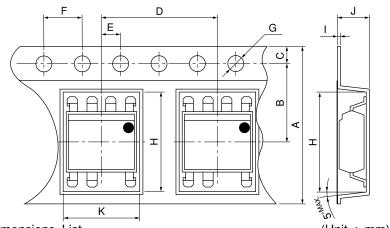
Package materials

Carrier tape : A-PET (with anti-static material)

Cover tape : PET (three layer system)

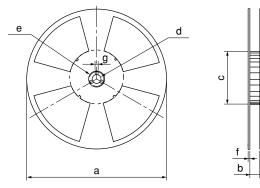
Reel : PS

Carrier tape structure and Dimensions



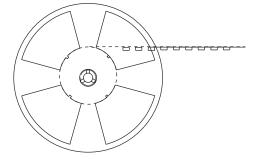
Dimensions List (Unit : mn							
А	В	С	D	Е	F	G	
16.0 <sup>±0.3</sup>	$7.5^{\pm 0.1}$	$1.75^{\pm 0.1}$	$12.0^{\pm0.1}$	$2.0^{\pm 0.1}$	$4.0^{\pm 0.1}$	φ1.5 <sup>+0.1</sup>	
Н	Ι	J	K				
$10.4^{\pm 0.1}$	$0.4^{\pm 0.05}$	$4.2^{\pm 0.1}$	$10.2^{\pm 0.1}$				

Reel structure and Dimensions

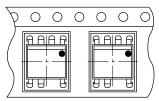


Dimensio	ns List	(U	nit : mm)
а	b	с	d
330	$17.5^{\pm 1.5}$	$100^{\pm 1.0}$	13 <sup>±0.5</sup>
e	f	g	
23 <sup>±1.0</sup>	$2.0^{\pm 0.5}$	$2.0^{\pm 0.5}$	

## Direction of product insertion



Pull-out direction



[Packing : 1 000pcs/reel]

# SHARP

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- --- Personal computers
- --- Office automation equipment
- --- Telecommunication equipment [terminal]
- --- Test and measurement equipment
- --- Industrial control
- --- Audio visual equipment
- --- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- --- Space applications
- --- Telecommunication equipment [trunk lines]
- --- Nuclear power control equipment
- --- Medical and other life support equipment (e.g., scuba).

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